

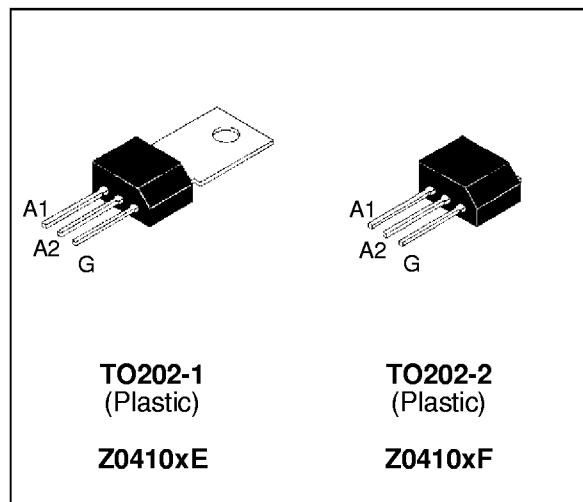
## STANDARD TRIACS

### FEATURES

- $I_{T(RMS)} = 4A$
- $V_{DRM} = 400V$  to  $800V$
- $I_{GT} \leq 25mA$

### DESCRIPTION

The Z0410xE/F series of triacs uses a high performance TOP GLASS PNP technology. These parts are intended for general purpose switching and phase control applications.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$I_{T(RMS)}$	RMS on-state current (360° conduction angle)	Z0410xE/F $T_c = 75^\circ C$	4	A
		Z0410xF $T_a = 25^\circ C$	0.95	
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25^\circ C$ )	$t_p = 8.3$ ms	22	A
		$t_p = 10$ ms	20	
$I^2t$	$I^2t$ Value for fusing	$t_p = 10$ ms	2	$A^2s$
$di/dt$	Critical rate of rise of on-state current $I_G = 50$ mA $di_G/dt = 0.1$ A/ $\mu s$ .	Repetitive F = 50 Hz	10	A/ $\mu s$
		Non Repetitive	50	
$T_{stg}$ $T_j$	Storage and operating junction temperature range		- 40, + 150 - 40, + 125	$^\circ C$
TI	Maximum lead temperature for soldering during 10s at 4.5mm from case		260	$^\circ C$

Symbol	Parameter	Voltage				Unit
		D	M	S	N	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125^\circ C$	400	600	700	800	V

## Z0410xE/F

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit	
Rth(j-a)	Junction to ambient	Z0410xE	80	°C/W
		Z0410xF	100	
Rth(j-c)	Junction to case for D.C	10	°C/W	
Rth(j-c)	Junction to case for A.C 360° conduction angle (F=50Hz)	7.5	°C/W	

### GATE CHARACTERISTICS (maximum values)

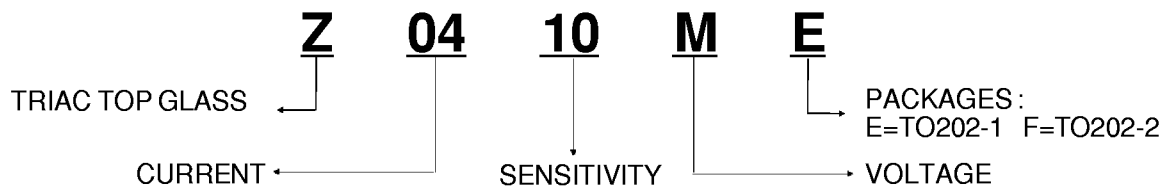
$P_{G(AV)} = 0.2 \text{ W}$   $P_{GM} = 3 \text{ W}$  ( $t_p = 20 \mu\text{s}$ )  $I_{GM} = 1.2 \text{ A}$  ( $t_p = 20 \mu\text{s}$ )

### ELECTRICAL CHARACTERISTICS

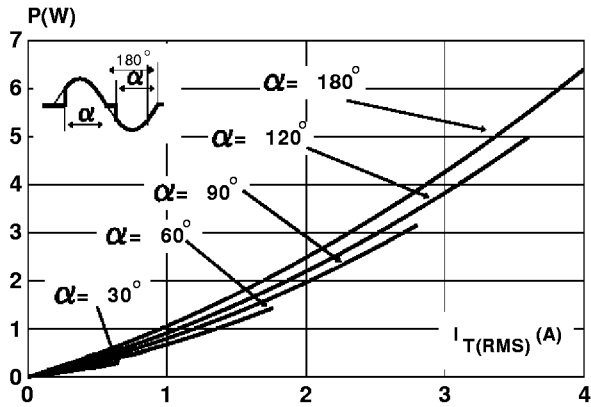
Symbol	Test Conditions	Quadrant		Sensitivity		Unit
					10	
$I_{GT}$	$V_D = 12\text{V (DC)}$ $R_L = 33\Omega$ $T_j = 25^\circ\text{C}$	I-II-III-IV	MAX		25	mA
$V_{GT}$	$V_D = 12\text{V (DC)}$ $R_L = 33\Omega$ $T_j = 25^\circ\text{C}$	I-II-III-IV	MAX		1.5	V
$V_{GD}$	$V_D = V_{DRM}$ $R_L = 3.3\text{k}\Omega$ $T_j = 125^\circ\text{C}$	I-II-III-IV	MIN		0.2	V
tgt	$V_D = V_{DRM}$ $I_G = 40\text{mA}$ $I_T = 5.5\text{A}$ $di_G/dt = 0.5\text{A}/\mu\text{s}$ $T_j = 25^\circ\text{C}$	I-II-III-IV	TYP		2	$\mu\text{s}$
$I_H^*$	$I_T = 50 \text{ mA}$ Gate open $T_j = 25^\circ\text{C}$		MAX		25	mA
$I_L$	$I_G = 1.2 I_{GT}$ $T_j = 25^\circ\text{C}$	I-III-IV	TYP		25	mA
		II	TYP		50	
$V_{TM}^*$	$I_{TM} = 5.5\text{A}$ $t_p = 380\mu\text{s}$ $T_j = 25^\circ\text{C}$		MAX		2	V
$I_{DRM}$ $I_{RRM}$	$V_D = V_{DRM}$ $V_R = V_{RRM}$ $T_j = 25^\circ\text{C}$		MAX		5	$\mu\text{A}$
			MAX		200	
dV/dt *	$V_D = 67\% V_{DRM}$ Gate open $T_j = 110^\circ\text{C}$		MIN		200	V/ $\mu\text{s}$
			TYP		400	
(dV/dt)c *	(di/dt)c = 1.8 A/ms $T_j = 110^\circ\text{C}$		MIN		5	V/ $\mu\text{s}$

\* For either polarity of electrode  $A_2$  voltage with reference to electrode  $A_1$

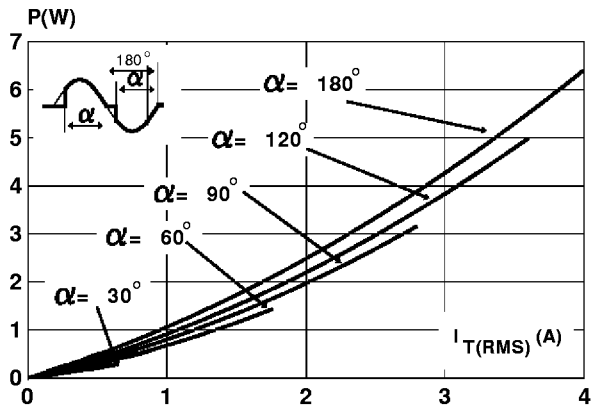
### ORDERING INFORMATION



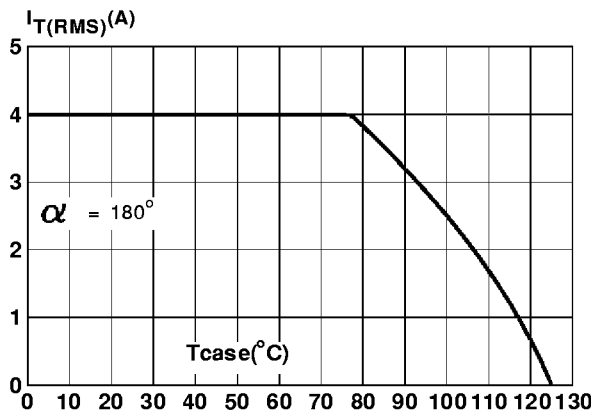
**Fig.1** : Maximum RMS power dissipation versus RMS on-state current.



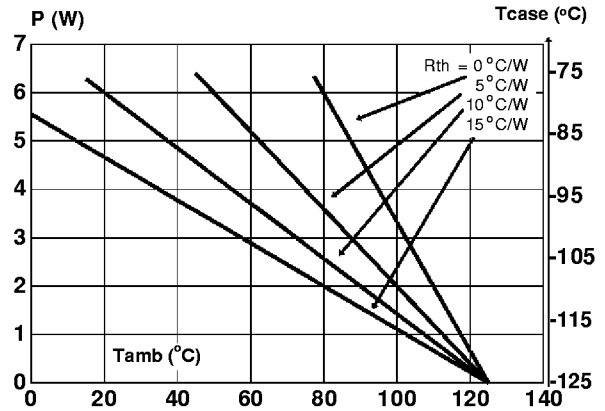
**Fig.3** : Maximum RMS power dissipation versus RMS on-state current.



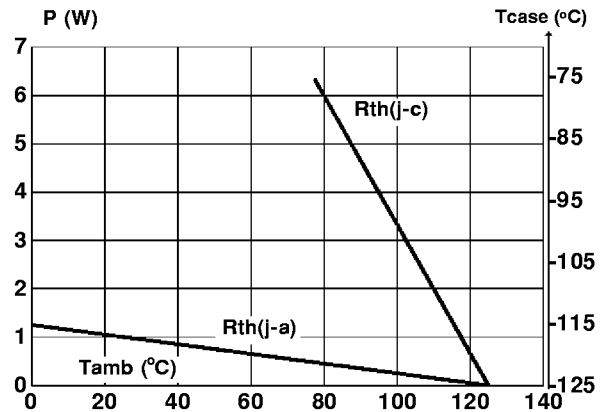
**Fig.5** : RMS on-state current versus case temperature (TO202-1).



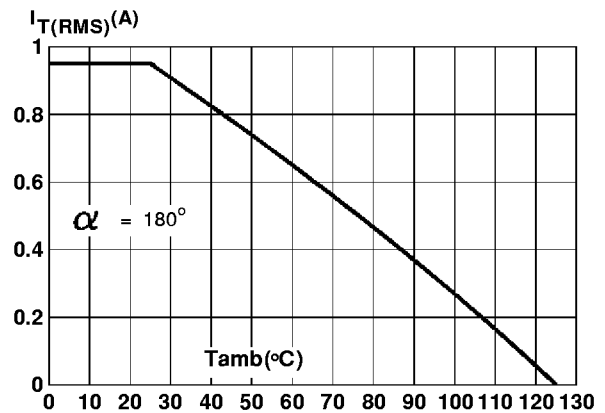
**Fig.2** : Correlation between maximum RMS power dissipation and maximum allowable temperature (Tamb and Tcase) for different thermal resistances heatsink + contact (TO202-1).



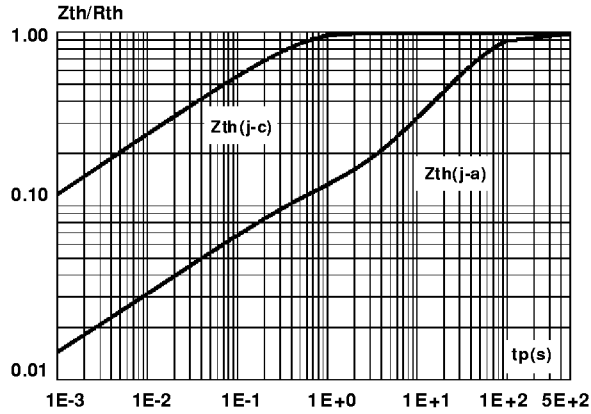
**Fig.4** : Correlation between maximum RMS power dissipation and maximum allowable temperature (Tamb and Tcase) (TO202-2).



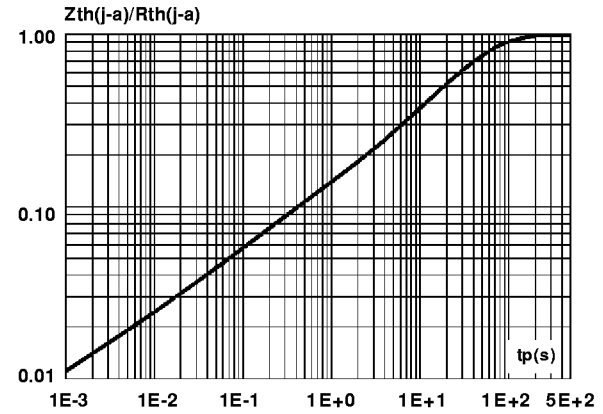
**Fig.6** : RMS on-state current versus case temperature (TO202-2).



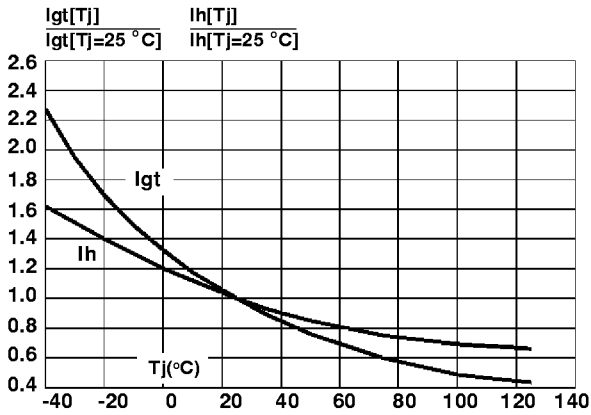
**Fig.6** : Relative variation of thermal impedance versus pulse duration (TO202-1).



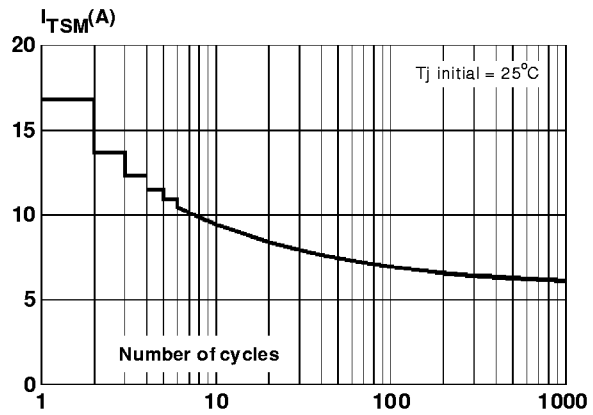
**Fig.7** : Relative variation of thermal impedance junction to ambient versus pulse duration (TO202-2).



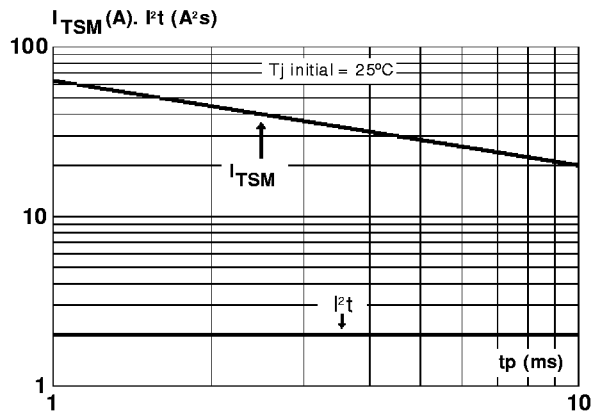
**Fig.9** : Relative variation of gate trigger current and holding current versus junction temperature.



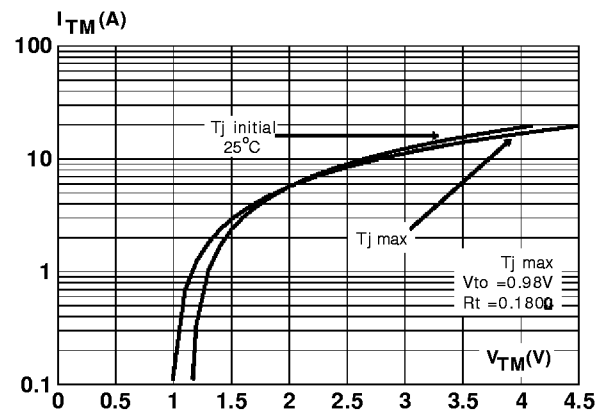
**Fig.10** : Non repetitive surge peak on-state current versus number of cycles.



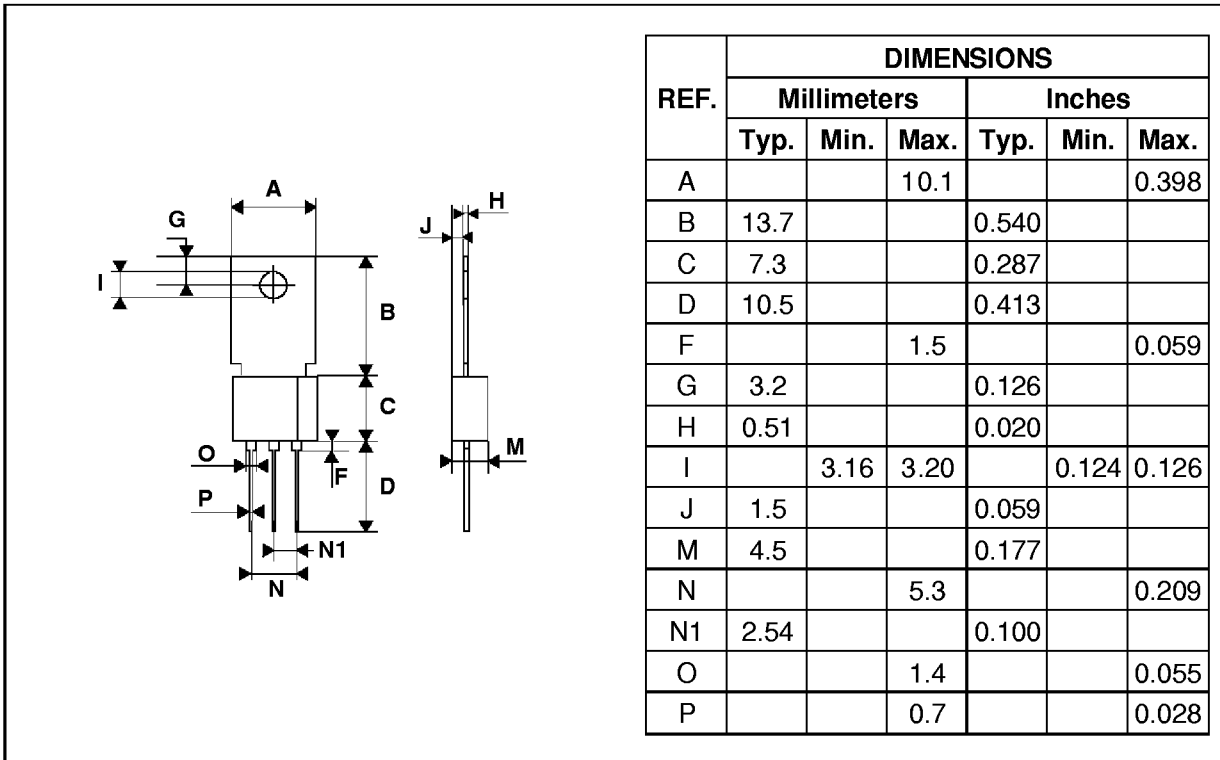
**Fig.11** : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t_p \leq 10$ ms, and corresponding value of  $I^2t$ .



**Fig.12** : On-state characteristics (maximum values).



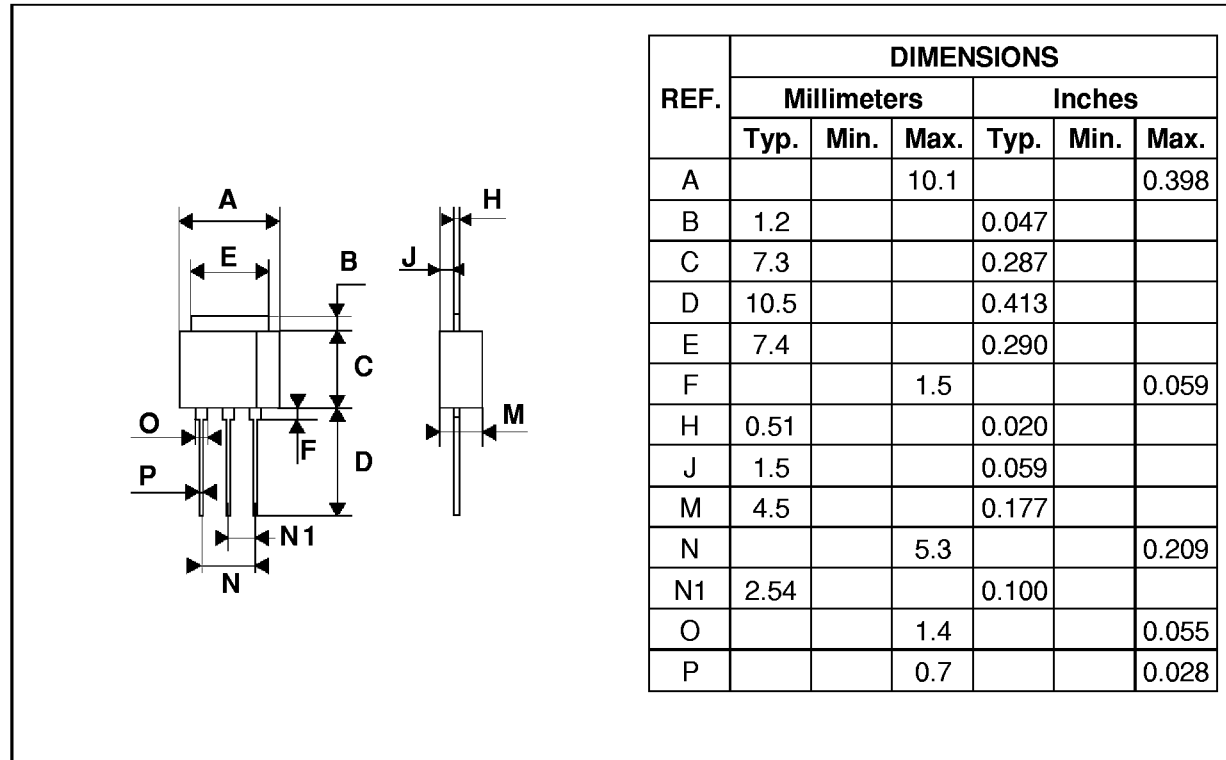
**PACKAGE MECHANICAL DATA**  
 TO202-1 (Plastic)



Marking : type number  
 Weight : 1.4 g

**Z0410xE/F**

**PACKAGE MECHANICAL DATA**  
TO202-2 (Plastic)



Marking : type number  
Weight : 1.0 g

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